

CLAIMS

What is claimed is:

1. A lead frame comprising:
a plurality of leads, including at least one lead having:
a first bonding region,
a second bonding region, and
a severance region located between the first bonding region and the second bonding region, the severance region being configured to facilitate separation of the first bonding region from the second bonding region.
2. The lead frame of claim 1, wherein the severance region includes a notch in the at least one lead.
3. The lead frame of claim 1, wherein each of the plurality of leads includes a first bonding region, a second bonding region, and a severance region configured to facilitate separation of the first and second bonding regions.
4. The lead frame of claim 3, wherein each severance region includes a notch.
5. A lead frame for an integrated circuit package, the lead frame comprising:
a die paddle configured for attachment to a semiconductor die; and
a plurality of conductive elements, each having at least two bonding regions arranged in a grid array about the die paddle, the grid array including a first peripheral row of bonding regions spaced about a periphery of the die paddle and at least one other peripheral row of bonding regions spaced outwardly from the first peripheral row of bonding regions.

6. A lead frame strip, comprising:
a plurality of longitudinally arranged lead frames, each lead frame including an outer frame portion bearing a plurality of inwardly extending, cantilevered leads, each lead of the plurality having thereon at least two longitudinally spaced locations separated by a severance region comprising a notch extending laterally across each lead.

7. The lead frame strip of claim 6, wherein each outer frame portion further bears a die paddle substantially centered therein.

8. The lead frame strip of claim 6, wherein the plurality of inwardly extending, cantilevered leads is located on a plurality of sides of each outer frame portion.

9. The lead frame strip of claim 6, wherein the plurality of inwardly extending, cantilevered leads is located on four sides of each outer frame portion.